L Number	Hits	Search Text	DB	Time stamp
1	2	(flexible near press) and wafer and (bond or bonding)	USPAT;	2004/06/23 22:32
		and (bump or bumps)	US-PGPUB;	
			EPO;	
			DERWENT;	
			IBM_TDB	
2	1	"flexible bladder press" and wafer and (bond or bonding)	USPAT;	2004/06/23 22:38
		and (bump or bumps)	US-PGPUB;	
			EPO;	
	:		DERWENT;	
			IBM_TDB	
3	0	20030148596.URPN.	USPAT	2004/06/23 22:33
4	2	"flexible bladder press" and wafer	USPAT;	2004/06/23 22:58
		-	US-PGPUB;	
			EPO;	
			DERWENT;	
			IBM TDB	
7	8179	press and wafer and bond\$3	USPĀT;	2004/06/24 01:01
		-	US-PGPUB;	
			EPO;	
			DERWENT;	
			IBM_TDB	
8	108	press and (wafer adj bond\$3) and (stack or 3-D)	USPAT;	2004/06/23 22:58
			US-PGPUB;	
			EPO;	
			DERWENT;	
			IBM_TDB	
9	525	press and (wafer adj bond\$3)	USPAT;	2004/06/23 22:40
			US-PGPUB;	
			EPO;	
			DERWENT;	
			IBM_TDB	
10	231	press and (wafer adj bond\$3) and (stack or 3-D or	USPĀT;	2004/06/23 22:41
		dimensional)	US-PGPUB;	
			EPO;	
			DERWENT;	
			IBM_TDB	
	0	(press and (wafer adj bond\$3) and (stack or 3-D)) and	USPAT;	2004/06/23 22:41
		(flexible near press)	US-PGPUB;	
			EPO;	
			DERWENT;	
			IBM_TDB	
12	I	(press and (wafer adj bond\$3) and (stack or 3-D)) and	USPAT;	2004/06/23 22:41
		(bladder near press)	US-PGPUB;	
			EPO;	
			DERWENT;	
			IBM_TDB	
13	7	(press and wafer and bond\$3) and (bladder near press)	USPAT;	2004/06/23 22:57
			US-PGPUB;	
			EPO;	
			DERWENT;	
			IBM_TDB	
14	18	(press and wafer and bond\$3) and (pressure near	USPAT;	2004/06/23 22:57
		bladder)	US-PGPUB;	
			EPO;	
			DERWENT;	
			IBM_TDB	

15	29210	pressure and wafer and bond\$3	USPAT;	2004/06/23 22:57
13	2,72,10	pressure and water and bolidas	US-PGPUB;	2004/00/25 22.57
			ł	
			EPO;	
1			DERWENT;	
1.7	400		IBM_TDB	0004/07/00 00 50
17	420	pressure and (wafer adj bond\$3) and (stack or 3-D)	USPAT;	2004/06/23 22:58
			US-PGPUB;	
			EPO;	
			DERWENT;	
1			IBM_TDB	
18	0	(pressure and (wafer adj bond\$3) and (stack or 3-D))	USPAT;	2004/06/23 22:58
	-	and (pressure near bladder)	US-PGPUB;	
			EPO;	
			DERWENT;	
			IBM_TDB	
19	0	"flexible pressure bladder" and wafer	USPAT;	2004/06/23 22:59
			US-PGPUB;	
			EPO;	
			DERWENT;	
			IBM_TDB	
21	307	autoclave and wafer and bonding	USPĀT;	2004/06/24 00:31
		0	US-PGPUB;	
	1		EPO;	
			DERWENT;	
1			IBM_TDB	
22	277	(autoclave and wafer and bonding) and pressure	USPAT;	2004/06/24 00:11
		(autobiavo ana water ana portantg) ana pressare	US-PGPUB;	2001/00/2100.11
			EPO;	
			DERWENT;	
			IBM_TDB	
16	55	(pressure and wafer and bond\$3) and (pressure near	USPAT;	2004/06/24 00:12
		bladder)	US-PGPUB;	200 400,2100.12
		J. adder /	EPO;	
	1		DERWENT;	
1			IBM TDB	
23	0	6475357.URPN.	USPAT	2004/06/24 00:20
24	3	("5429733" "5447615" "6080050").PN.	USPAT	2004/06/24 00:20
25	0	6197665.URPN.	USPAT	2004/06/24 00:20
26	6	("5090246" "5148265" "5148266" "5227812"	USPAT	2004/06/24 00:22
		"5282312" "5398863").PN.	OSIAI	2004/00/24 00.22
20	79	"pressure bladder" and wafer	USPAT;	2004/06/24 00:28
20	'	pressure bladder and water	US-PGPUB;	2004/00/24 00:26
			EPO;	
			DERWENT;	
27	20	("mmooo	IBM_TDB	0004/07/04 00 01
21	30	("pressure bladder" and wafer) not ((pressure and wafer	USPAT;	2004/06/24 00:31
		and bond\$3) and (pressure near bladder))	US-PGPUB;	
			EPO;	
			DERWENT;	
1 20	0.7	/1	IBM_TDB	0004633
28	307	(autoclave and wafer and bonding) not ("pressure	USPAT;	2004/06/24 00:58
		bladder" and wafer) not ((pressure and wafer and	US-PGPUB;	
		bond\$3) and (pressure near bladder))	EPO;	
			DERWENT;	
	_]		IBM_TDB	
29	0	20030027373.URPN.	USPAT	2004/06/24 00:33

	- 		T	
30	9	vertical adj stack adj integration	USPAT;	2004/06/24 00:58
			US-PGPUB;	
			EPO;	
			DERWENT;	,
			IBM_TDB	
31	8	(vertical adj stack adj integration) not (autoclave and	USPAT;	2004/06/24 01:02
		wafer and bonding) not ("pressure bladder" and wafer)	US-PGPUB;	
		not ((pressure and wafer and bond\$3) and (pressure	EPO;	
		near bladder))	DERWENT;	
			IBM_TDB	
32	1337	wafer\$4wafer	USPAT;	2004/06/24 01:01
			US-PGPUB;	
			EPO;	
			DERWENT;	
			IBM TDB	
33	241	wafer\$4wafer and stack	USPĀT;	2004/06/24 01:02
			US-PGPUB;	
			EPO;	
			DERWENT;	
			IBM_TDB	
34	26	wafer\$4wafer and stack near vertical	USPAT;	2004/06/24 01:02
			US-PGPUB;	200 400,2101.02
			EPO;	
			DERWENT;	
			IBM_TDB	
35	17	(wafer\$4wafer and stack near vertical) not (vertical adj	USPAT;	2004/06/24 01:22
	1,	stack adj integration) not (autoclave and wafer and	US-PGPUB;	2004/00/24 01.22
		bonding) not ("pressure bladder" and wafer) not	EPO;	
		((pressure and wafer and bond\$3) and (pressure near	DERWENT;	
		bladder))	IBM_TDB	
36	508	438/51	USPAT;	2004/06/24 01:21
30		150/51	US-PGPUB;	2004/00/24 01.21
			EPO;	
			DERWENT;	
			IBM TDB	
37	16	438/51 and (bond or bonding) and wafer and stack and	USPAT;	2004/06/24 01:21
37		pressure	US-PGPUB;	2004/00/24 01:21
		pressure	EPO;	
			DERWENT; IBM TDB	
38	16	(438/51 and (bond or bonding) and wafer and stack and	USPAT;	2004/06/24 01:12
		pressure) not ((wafer\$4wafer and stack near vertical) not	US-PGPUB;	2007/00/24 01:12
		(vertical adj stack adj integration) not (autoclave and	EPO;	
		wafer and bonding) not ("pressure bladder" and wafer)	DERWENT;	
		not ((pressure and wafer and bond\$3) and (pressure	IBM TDB	
		near bladder)))	I TOINT I DO	
39	686	438/52	USPAT;	2004/06/24 01:23
37	000	130/32	US-PGPUB;	2004/00/24 U1:23
			EPO;	
			DERWENT;	
40	25	438/52 and (hand or handing) and water and start and	IBM_TDB	2004/06/24 01 02
10	25	438/52 and (bond or bonding) and wafer and stack and	USPAT;	2004/06/24 01:23
		pressure	US-PGPUB;	
			EPO;	
			DERWENT;	
	L		IBM_TDB	

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## and stack and pressure) not (waferSwafer and stack not pressure) bladder and wafer not obnoding) not ("pressure bladder" and wafer) not ((pressure and wafer and bonding) not ("pressure bladder") USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB USPAT;	41	19	(438/52 and (bond or bonding) and wafer and stack and	USPAT;	2004/06/24 01:23
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42 43 43 438/53 438/					
bladder" and wafer) not ((pressure and wafer and bonds) a) and (pressure near bladder)) 438/53 20				i	
2004/06/24 01:24 2004/06/24		1		IBM_TDB	
43					
13					
43	42	612	438/53		2004/06/24 01:24
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20				EPO;	
43 20 438/53 and (bond or bonding) and wafer and stack and pressure				DERWENT;	
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12	43	20	438/53 and (bond or bonding) and wafer and stack and	USPAT;	2004/06/24 01:24
12			pressure	US-PGPUB;	
12				EPO;	
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Boladder)					
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bonding) and wafer and stack and pressure) not (438/51 and (bond or bonding) and wafer and stack and pressure) not (wafer\$4wafer and stack near vertical) not (vertical adj stack adj integration) not (autoclave and wafer and bonding) not ("pressure bladder" and wafer) not ((pressure and wafer and bonds3) and (pressure near bladder)) 48					
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48 49 40 41 42 43					
49	48	0	• •	USPAT	2004/06/24 01:33
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"4618763" "4702936" "4706166" "4721938" "4761681" "4784721" "5070026" "5071510" "5130894" "5236118" "5262351" "5270261" "5273940" "5284796" "5324687" "5385632" "5424920" "5426072" "5432729" "5457879" "5489554" "5502667" "5534465" "5563084" "5581498" "5637536" "5656552" "5694588" "5760478" "5793115" "5880010" "5902118"					
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50	1642	438/107	USPAT;	2004/06/24 01:47
	10.2	133/107	US-PGPUB;	2004/00/24 01.17
			EPO;	
			DERWENT;	
			IBM TDB	
51	71	438/107 and (bond or bonding) and wafer and stack and	USPĀT;	2004/06/24 01:47
		pressure	US-PGPUB;	
			EPO;	
			DERWENT;	
			IBM_TDB	
52	43	(438/107 and (bond or bonding) and wafer and stack	USPAT;	2004/06/24 01:48
		and pressure) not (438/106 and (bond or bonding) and	US-PGPUB;	
		wafer and stack and pressure) not (438/53 and (bond or	EPO;	
		bonding) and wafer and stack and pressure) not (438/52	DERWENT;	
		and (bond or bonding) and wafer and stack and pressure)	IBM_TDB	
	·	not (438/51 and (bond or bonding) and wafer and stack		
		and pressure) not (wafer\$4wafer and stack near vertical)		
		not (vertical adj stack adj integration) not (autoclave and wafer and bonding) not ("pressure bladder" and wafer)		
		not ((pressure and wafer and bond\$3) and (pressure		
		near bladder))		
53	892	438/109	USPAT;	2004/06/24 01:53
	0,7	10 3, 10 7	US-PGPUB;	2004/00/24 01.33
			EPO;	
			DERWENT;	
			IBM_TDB	
54	69	438/109 and (bond or bonding) and wafer and stack and	USPĀT;	2004/06/24 01:54
		pressure	US-PGPUB;	-
			EPO;	
			DERWENT;	
		(4004000 144 1 1 1 1 1 1 1 1 1 1 1 1 1 1	IBM_TDB	
55	41	(438/109 and (bond or bonding) and wafer and stack	USPAT;	2004/06/24 01:54
		and pressure) not (438/107 and (bond or bonding) and	US-PGPUB;	
		wafer and stack and pressure) not (438/106 and (bond or	EPO;	
		bonding) and wafer and stack and pressure) not (438/53 and (bond or bonding) and wafer and stack and pressure)	DERWENT;	
		not (438/52 and (bond or bonding) and wafer and stack	IBM_TDB	
		and pressure) not (438/51 and (bond or bonding) and		
		wafer and stack and pressure) not (wafer\$4wafer and		
		stack near vertical) not (vertical adj stack adj integration)		
		not (autoclave and wafer and bonding) not ("pressure		
		bladder" and wafer) not ((pressure and wafer and		
		bond\$3) and (pressure near bladder))		
56	1250	438/455	USPAT;	2004/06/24 01:58
			US-PGPUB;	
			EPO;	
			DERWENT;	
57		400/455 1/3 1 1 1 1 1	IBM_TDB	
57	110	438/455 and (bond or bonding) and wafer and stack and	USPAT;	2004/06/24 01:58
		pressure	US-PGPUB;	
,			EPO;	
			DERWENT;	
	L		IBM_TDB	

[50		(400)455	1	
58	72	(438/455 and (bond or bonding) and wafer and stack	USPAT;	2004/06/24 01:58
		and pressure) not (438/109 and (bond or bonding) and	US-PGPUB;	
		wafer and stack and pressure) not (438/107 and (bond or	EPO;	
		bonding) and wafer and stack and pressure) not	DERWENT;	
		(438/106 and (bond or bonding) and wafer and stack	IBM_TDB	
		and pressure) not (438/53 and (bond or bonding) and		
		wafer and stack and pressure) not (438/52 and (bond or	1	
		bonding) and wafer and stack and pressure) not (438/51		
		and (bond or bonding) and wafer and stack and pressure)		
	-	not (wafer\$4wafer and stack near vertical) not (vertical		
		adj stack adj integration) not (autoclave and wafer and		
		bonding) not ("pressure bladder" and wafer) not		
		((pressure and wafer and bond\$3) and (pressure near		
		bladder))		
59	333	438/456	USPAT;	2004/06/24 01:59
		100,100	US-PGPUB;	2004/00/24 01.37
			EPO;	
			DERWENT;	
60	27	490/456 1 (1 1 1 1 1 1 1	IBM_TDB	0004/04/04/04
60	27	438/456 and (bond or bonding) and wafer and stack and	USPAT;	2004/06/24 01:59
		pressure	US-PGPUB;	
			EPO;	
			DERWENT;	
			IBM_TDB	
61	3	(438/456 and (bond or bonding) and wafer and stack	USPAT;	2004/06/24 01:59
		and pressure) not (438/455 and (bond or bonding) and	US-PGPUB;	
		wafer and stack and pressure) not (438/109 and (bond or	EPO;	
		bonding) and wafer and stack and pressure) not	DERWENT;	
		(438/107 and (bond or bonding) and wafer and stack	IBM_TDB	
		and pressure) not (438/106 and (bond or bonding) and		
		wafer and stack and pressure) not (438/53 and (bond or		
		bonding) and wafer and stack and pressure) not (438/52		
		and (bond or bonding) and wafer and stack and pressure)		
		not (438/51 and (bond or bonding) and wafer and stack		
		and pressure) not (wafer\$4wafer and stack near vertical)		
		not (vertical adj stack adj integration) not (autoclave and		
		wafer and bonding) not ("pressure bladder" and wafer)		
		not ((pressure and wafer and bond\$3) and (pressure		
		near bladder))		
62	138	438/457	USPAT;	2004/06/24 01:59
			US-PGPUB;	2007/00/27 01.37
			EPO;	
			DERWENT;	
			•	
63	11	438/457 and (hand or handing) and surface and at 1	IBM_TDB	0004/07/04 03 70
00	11	438/457 and (bond or bonding) and wafer and stack and	USPAT;	2004/06/24 01:59
		pressure	US-PGPUB;	
			EPO;	:
:			DERWENT;	
			IBM_TDB	

	,			
64	0	(438/457 and (bond or bonding) and wafer and stack and pressure) not (438/456 and (bond or bonding) and wafer and stack and pressure) not (438/455 and (bond or bonding) and wafer and stack and pressure) not (438/109 and (bond or bonding) and wafer and stack and pressure) not (438/107 and (bond or bonding) and wafer and stack and pressure) not (438/106 and (bond or bonding) and wafer and stack and pressure) not (438/53 and (bond or bonding) and wafer and stack and pressure) not (438/52 and (bond or bonding) and wafer and stack and pressure) not (438/51 and (bond or bonding) and wafer and stack and pressure) not (wafer\$4wafer and stack near vertical) not (vertical adj stack adj integration) not (autoclave and wafer and bonding) not ("pressure bladder" and wafer) not ((pressure and wafer and bond\$3) and (pressure near bladder))	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2004/06/24 01:59
65	1038	438/459	USPAT; US-PGPUB; EPO; DERWENT; IBM TDB	2004/06/24 02:00
66	60	438/459 and (bond or bonding) and wafer and stack and pressure	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2004/06/24 02:00
67	15	(438/459 and (bond or bonding) and wafer and stack and pressure) not (438/457 and (bond or bonding) and wafer and stack and pressure) not (438/456 and (bond or bonding) and wafer and stack and pressure) not (438/455 and (bond or bonding) and wafer and stack and pressure) not (438/109 and (bond or bonding) and wafer and stack and pressure) not (438/107 and (bond or bonding) and wafer and stack and pressure) not (438/106 and (bond or bonding) and wafer and stack and pressure) not (438/53 and (bond or bonding) and wafer and stack and pressure) not (438/52 and (bond or bonding) and wafer and stack and pressure) not (438/51 and (bond or bonding) and wafer and stack and pressure) not (wafer\$4wafer and stack near vertical) not (vertical adj stack adj integration) not (autoclave and wafer and bonding) not ("pressure bladder" and wafer) not ((pressure and wafer and bond\$3) and (pressure near bladder))	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2004/06/24 02:01
68	454	438/975	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2004/06/24 02:01
69	4	438/975 and (bond or bonding) and wafer and stack and pressure	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2004/06/24 02:02

70	3	(438/975 and (bond or bonding) and wafer and stack	USPAT;	2004/06/24 02:02
		and pressure) not (438/459 and (bond or bonding) and	US-PGPUB;	, , , , , , , , , , , , , , , , , , , ,
		wafer and stack and pressure) not (438/457 and (bond or	EPO;	
		bonding) and wafer and stack and pressure) not	DERWENT;	
		(438/456 and (bond or bonding) and wafer and stack	IBM_TDB	
		and pressure) not (438/455 and (bond or bonding) and	10111_100	
		wafer and stack and pressure) not (438/109 and (bond or		
		bonding) and wafer and stack and pressure) not		
		(438/107 and (bond or bonding) and wafer and stack		
		and pressure) not (438/106 and (bond or bonding) and		
		wafer and stack and pressure) not (438/53 and (bond or		
		bonding) and wafer and stack and pressure) not (438/52		
		and (bond or bonding) and wafer and stack and pressure)		
		not (438/51 and (bond or bonding) and wafer and stack		
		and pressure) not (wafer\$4wafer and stack near vertical)		
		not (vertical adj stack adj integration) not (autoclave and		
		wafer and bonding) not ("pressure bladder" and wafer)		
		not ((pressure and wafer and bond\$3) and (pressure		
71	704	near bladder))	LICDATE	2004/04/04 2000
71	704	438/977	USPAT;	2004/06/24 02:01
			US-PGPUB;	
			EPO;	
			DERWENT;	
70		400/077	IBM_TDB	
72	32	438/977 and (bond or bonding) and wafer and stack and	USPAT;	2004/06/24 02:02
		pressure	US-PGPUB;	
			EPO;	
			DERWENT;	
70	_	(400/077 1/1 1 1 1)) ()	IBM_TDB	
73	4	(438/977 and (bond or bonding) and wafer and stack	USPAT;	2004/06/24 02:02
		and pressure) not (438/975 and (bond or bonding) and	US-PGPUB;	
		wafer and stack and pressure) not (438/459 and (bond or	EPO;	
		bonding) and wafer and stack and pressure) not	DERWENT;	
		(438/457 and (bond or bonding) and wafer and stack	IBM_TDB	
	1	and pressure) not (438/456 and (bond or bonding) and		
		wafer and stack and pressure) not (438/455 and (bond or		
		bonding) and wafer and stack and pressure) not		
		(438/109 and (bond or bonding) and wafer and stack		
		and pressure) not (438/107 and (bond or bonding) and		
		wafer and stack and pressure) not (438/106 and (bond or		
		bonding) and wafer and stack and pressure) not (438/53		
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		not (438/52 and (bond or bonding) and wafer and stack		
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		wafer and stack and pressure) not (wafer\$4wafer and		
		stack near vertical) not (vertical adj stack adj integration)		
]	not (autoclave and wafer and bonding) not ("pressure		
		bladder" and wafer) not ((pressure and wafer and		
_	L	bond\$3) and (pressure near bladder))		